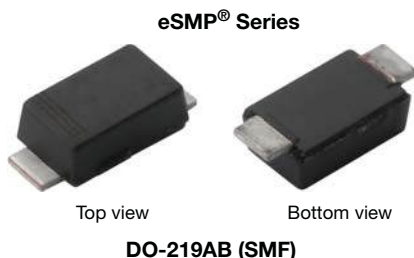


Surface Mount Schottky Barrier Rectifier



FEATURES

- Low profile package
- Ideal for automated placement
- Low forward voltage drop, low power losses
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Wave and reflow solderable
- AEC-Q101 qualified available
 - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see www.vishay.com/doc299912



RoHS
COMPLIANT
HALOGEN
FREE

TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

MECHANICAL DATA

Case: DO-219AB (SMF)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

Polarity: Color band denotes the cathode end

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	2.0 A
V_{RRM}	40 V
I_{FSM}	50 A
V_F at $I_F = 2.0$ A ($T_A = 125$ °C)	0.43 V
T_J max.	150 °C
Package	DO-219AB (SMF)
Diode variations	Single die

MAXIMUM RATINGS ($T_A = 25$ °C unless otherwise noted)			
PARAMETER	SYMBOL	SS2FL4	UNIT
Device marking code		2L4	
Maximum repetitive peak reverse voltage	V_{RRM}	40	V
Maximum average forward rectified current (fig. 1)	$I_{F(AV)}^{(1)}$	2.0	A
Non-repetitive peak forward surge current 8.3 ms single half sine-wave at $T_{J(init)} = 25$ °C	I_{FSM}	50	A
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150	°C

Note

⁽¹⁾ Free air, mounted on recommended copper pad area



ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I _F = 1.0 A	T _A = 25 °C	V _F ⁽¹⁾	0.43	-	V
	I _F = 2.0 A			0.50	0.58	
	I _F = 1.0 A	T _A = 125 °C		0.33	-	
	I _F = 2.0 A			0.43	0.51	
Reverse current	V _R = 40 V	T _A = 25 °C	I _R ⁽²⁾	-	220	μA
		T _A = 125 °C		8	14	mA
Typical junction capacitance	4.0 V, 1 MHz		C _J	125	-	pF

Notes

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
 (2) Pulse test: Pulse width $\leq 5\text{ ms}$

THERMAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	SS2FL4	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)(2)(3)}$	125	$^{\circ}\text{C/W}$
	$R_{\theta JM}^{(2)(3)}$	21	

Notes

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
 (2) Device mounted on FR4 PCB, 2 oz. standard footprint
 (3) Thermal resistance $R_{\theta JA}$ - junction to ambient; $R_{\theta JM}$ - junction to mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
SS2FL4-M3/H	0.015	H	3000	7" diameter plastic tape and reel
SS2FL4-M3/I	0.015	I	10 000	13" diameter plastic tape and reel
SS2FL4HM3/H ⁽¹⁾	0.015	H	3000	7" diameter plastic tape and reel
SS2FL4HM3/I ⁽¹⁾	0.015	I	10 000	13" diameter plastic tape and reel

Note

- (1) AEC-Q101 qualified

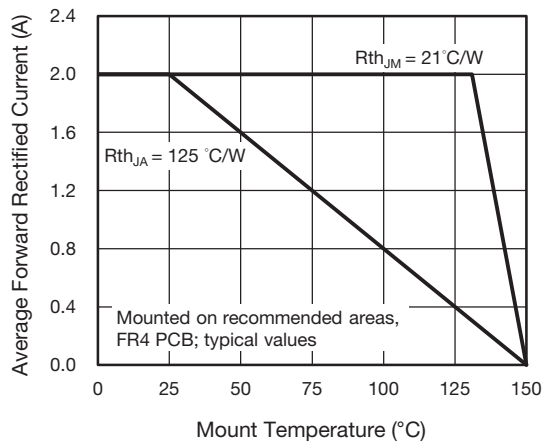
RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)


Fig. 1 - Typical Forward Current Derating Curve

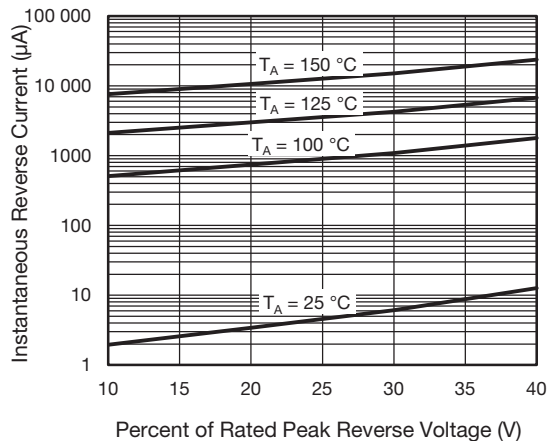


Fig. 4 - Typical Reverse Leakage Characteristics

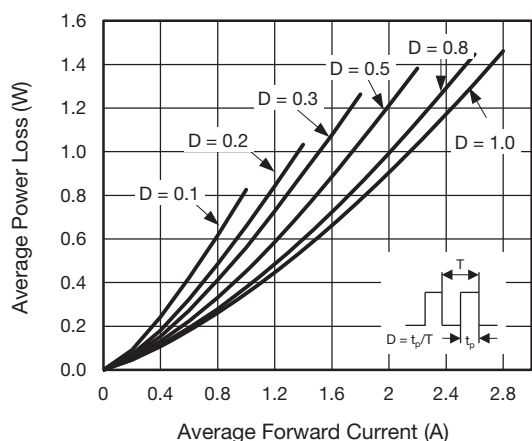


Fig. 2 - Forward Power Loss Characteristics

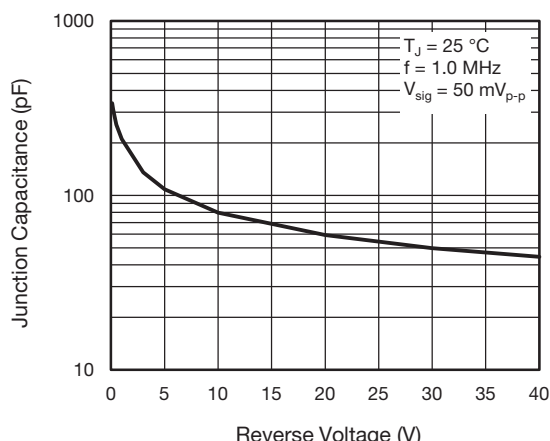


Fig. 5 - Typical Junction Capacitance

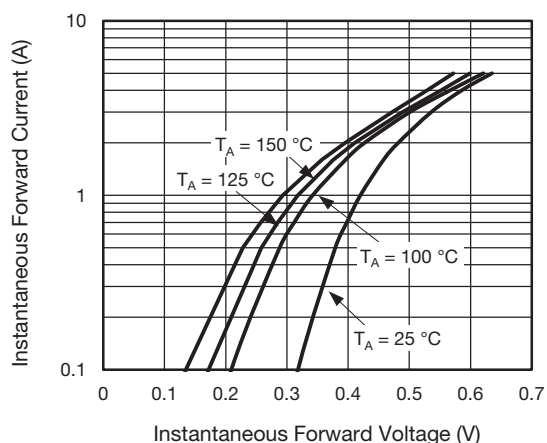


Fig. 3 - Typical Instantaneous Forward Characteristics

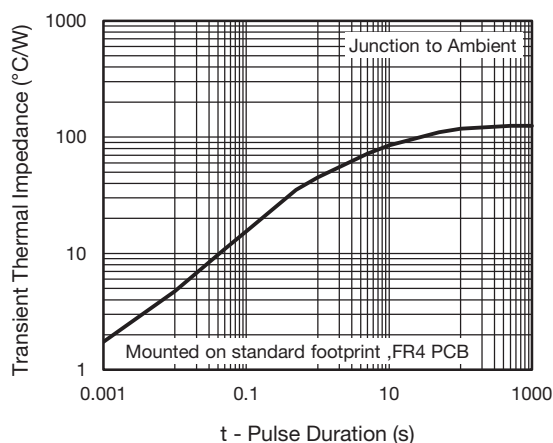
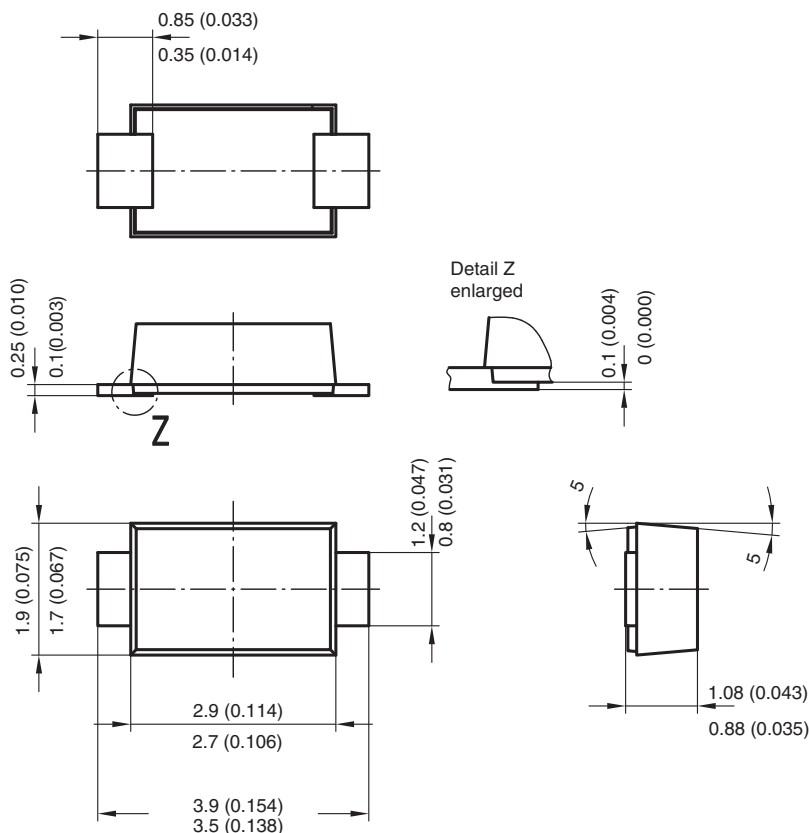
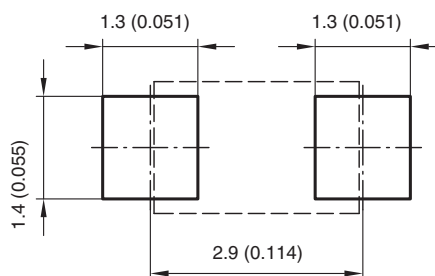


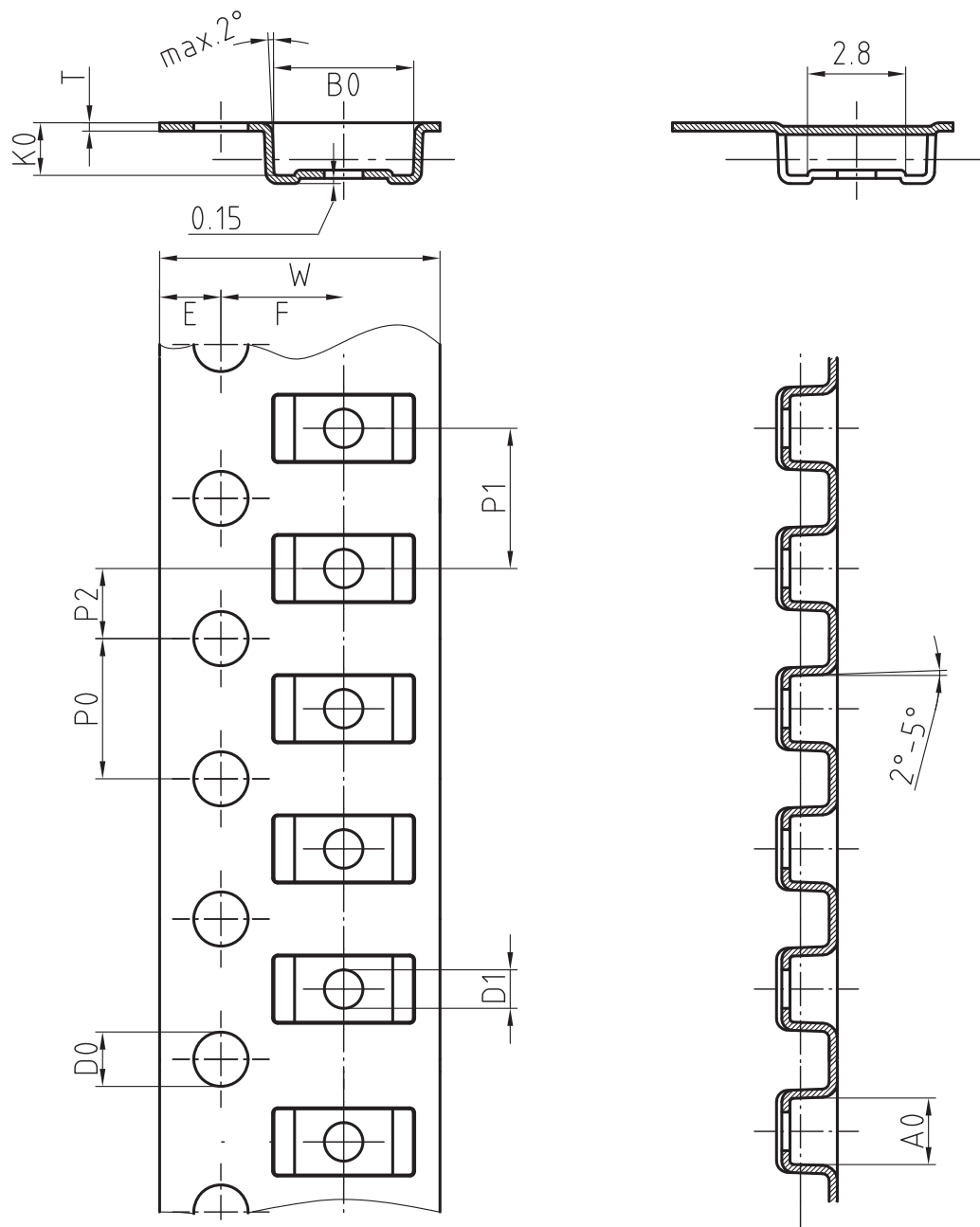
Fig. 6 - Typical Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS in millimeters (inches)


Foot print recommendation:



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Rev. 3 - Date: 13. March 2007
Document no.: S8-V-3915.01-001 (4)
17247

BLISTERTAPE DIMENSIONS in millimeters: **DO-219AB (SMF)**


Mat:	A0	B0	K0	W	T	P0	P2	P1	D0	D1	E	F
PS	1.9	4.0	1.5	8.0	0.235	4.0	2.0	4.0	1.5	1	1.75	3.5

Document-No.: S8-V-3717.02-001 (3)

18513



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